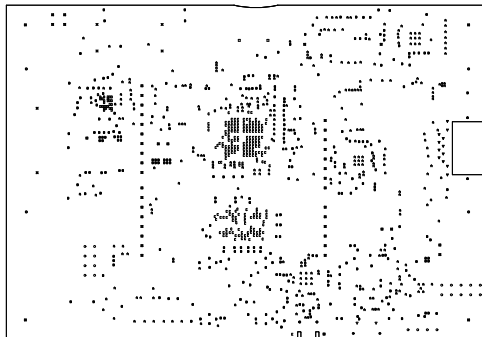
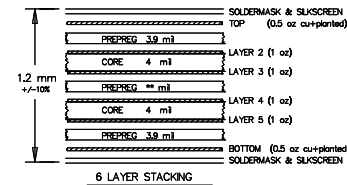


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
1.0	EDITION ORIGINALE	2008-**-**	***

5 IMPEDANCE TABLE

LAYER	TRACE (mil)	SPACING (mil)	IMPEDANCE (Single end)	IMPEDANCE (Differential)	TOLERANCE
1,6	5.0	N/A	55 OHM	N/A	+/-10%
4	4.0				
1,6	5.1	9.9	N/A	100 OHM	+/-10%
1,6	6.1	8.9	N/A	90 OHM	+/-10%

4 LAYER STACK-UP



Symbol	Hit Count	Finished Hole Size	Plated	Hole Length	Routed Path Length
D	27	0.15mm	PTH	-	-
C	219	0.20mm	PTH	-	-
A	354	0.25mm	PTH	-	-
B	349	0.31mm	PTH	-	-
⊙	2	0.61mm	PTH	1.30mm	0.69mm
□	2	0.71mm	PTH	-	-
✱	2	0.71mm	PTH	2.21mm	1.50mm
⊕	2	0.76mm	PTH	0.84mm	0.08mm
✱	1	0.76mm	PTH	1.50mm	0.74mm
▽	2	0.84mm	PTH	-	-
E	1	0.84mm	PTH	1.50mm	0.66mm
▽	12	0.89mm	PTH	-	-
○	22	0.91mm	PTH	-	-
⊗	45	1.02mm	PTH	-	-
✱	2	1.07mm	PTH	1.47mm	0.41mm
✱	4	2.01mm	PTH	-	-
⊕	4	3.51mm	PTH	-	-
⊕	4	4.50mm	PTH	-	-
1054 Total					


Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.  
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

PCB SPECIFICATIONS:

- A. MATERIAL; FR-4, ☒ TG-170 ☐ TG-150 ☐ TG-140  
B. MATERIAL FAMILY; N/A.  
C. SOLDERMASK COLOR; ☒ GREEN ☐ BLUE ☐ RED ☐ BLACK  
D. SILKSCREEN COLOR; ☒ WHITE ☐ YELLOW ☐ BLACK  
E. SURFACE FINISH; ☒ ENIG ☐ IMMERSION SILVER ☐ IMMERSION TIN  
☐ HASL ☐ HASL(PB-FREE) ☐ GOLDEN FINGER  
F. IMPEDANCE CONTROL; ☐ NO ☒ YES(SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)  
G. THROUGH VIA; PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDES.  
PLUG MATERIAL: ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.  
H. STACK-UP; SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

PCB REQUIREMENTS:

- THIS BOARD WILL CONFORM TO:  
IPC-A-600, CURRENT REV., CLASS II  
IPC-6012, CURRENT REV., CLASS II
- UNLESS OTHERWISE SPECIFIED ALL HOLE DIMENSIONS APPLY AFTER PLATING.  
ALL HOLES SHALL BE LOCATED WITHIN .003" DIAMETER OF TRUE POSITION.
- PLATED HOLE WALL THICKNESS SHALL NOT BE LESS THAN .001 INCH MINIMUM AVERAGE, WITH NO READING LESS THAN .0008 BY CORROSS SECTION.
- MATERIAL FR4 RATING 94V-0 MINIMUM EPOXY GLASS LAMINATE.
- BOARD SHALL BE LPI SOLDER MASKED OVER BARE COPPER BOTH SIDES PER IPC-SM-840 CLASS II.
- SILKSCREEN SHALL BE PERMANENT NON-CONDUCTIVE INK AND WITH NO OVERLAP ON ANY COMPONENT PAD OR THROUGH HOLE.
- MFGR. TO LEGIBLY ETCH OR STAMP/SCREEN WITH PERMANENT NON-CONDUCTIVE INK  
A. ULL CODE  
B. DATE CODE  
C. FLAMMABILITY RATING  
D. MFGR. LOGO  
E. SUCCESSFUL ELECTRICAL BOARD TEST.
- REMOVE THE FLASHS WHICH SMALLER THAN HOLE SIZE.
- REMOVE ALL SHAPE EDGES AND BURRS .005 MAXIMUM.
- PLEASE USE THE SUPPLIED IPC 356 NETLIST TO VERIFY BOARD BEFORE FABRICATING BOARD.

 DESIGNED BY SOFER www.sofer.com.cn Tel : +86 21 - 6482 6908 Mail: design@sofer.com.cn	LAYER:	COMPANY NAME	
	DESIGNER: Shelley	ST	
	DATE: 2016.02.18	PROJECT NAME	
		PROJECT NUMBER: DQ31-019A2	REV B

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ON: 2 PL DECIMALS + 3 PL DECIMALS + ANGLES + FRACTIONS +	SIGNATURES	DATE	LOGO		COMPANY NAME	
	DRAWN	YY-MM-DD	DRAWN		PROJECT NAME *	
	CHECKED	YY-MM-DD	CHECKED		TITLE	
	ENGRG	YY-MM-DD	ENGRG		SIZE B DWG NO *****	
ISSUED			ISSUED		SCALE 1:1	
					SHEET 1 OF 1	